

## DESCRIPTION

The 5N10 is the high cell density trenched N-ch MOSFETs, which provides excellent RDSON and efficiency for most of the small power switching and load switch applications.

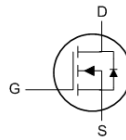
The 5N10 meet the RoHS and Green Product requirement with full function reliability approved.

Green Device Available  
Super Low Gate Charge  
Excellent Cdv/dt effect decline  
Advanced high cell density Trench technology

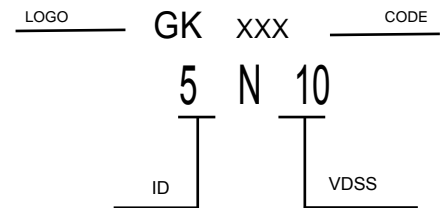
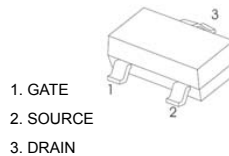
$V_{DS}$  100 V  
 $I_D$  5.0 A  
 $R_{DS(ON)}$  95 m $\Omega$

GK XXX  
5N10

### Equivalent Circuit



### SOT-23



## MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D@T_A=25^\circ\text{C}$	Continuous Drain Current, $V_{GS}$ @ 10V <sup>1</sup>	5.0	A
$I_D@T_A=70^\circ\text{C}$	Continuous Drain Current, $V_{GS}$ @ 10V <sup>1</sup>	3.2	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	12	A
$P_D@T_A=25^\circ\text{C}$	Total Power Dissipation <sup>3</sup>	2.5	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient <sup>1</sup>	---	74	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	80	$^\circ\text{C/W}$

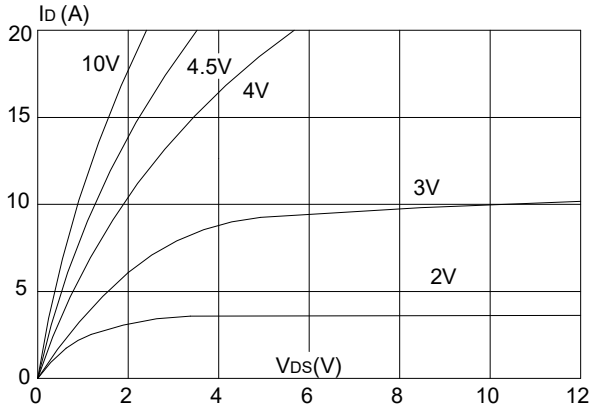
## Electrical Characteristics T<sub>J</sub>=25°C unless otherwise specified

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	100	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V,	-	-	1.0	μA
I <sub>GSS</sub>	Gate to Body Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V	-	-	±100	nA
<b>On Characteristics</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> V <sub>GS</sub> , I <sub>D</sub> 250μA	1.0	1.5	2.5	V
R <sub>DS(on)</sub>	Static Drain-Source on-Resistance <small>Note2</small>	V <sub>GS</sub> =10V, I <sub>D</sub> =3A	-	95	120	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =2A	-	98	137	mΩ
<b>Dynamic Characteristics</b>						
C <sub>iSS</sub>	Input Capacitance	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1.0MHz	-	765	-	pF
C <sub>oss</sub>	Output Capacitance		-	38	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	33	-	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =50V, I <sub>D</sub> =2A, V <sub>GS</sub> =10V	-	18	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	2.5	-	nC
Q <sub>gd</sub>	Gate-Drain("Miller") Charge		-	4	-	nC
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DS</sub> =50V, I <sub>D</sub> =3A, R <sub>G</sub> =1.8Ω, V <sub>GS</sub> =10V	-	7.5	-	ns
t <sub>r</sub>	Turn-on Rise Time		-	6	-	ns
t <sub>d(off)</sub>	Turn-off Delay Time		-	21	-	ns
t <sub>f</sub>	Turn-off Fall Time		-	9	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	5	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	12	A
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =3A	-	-	1.2	V
t <sub>rr</sub>	Body Diode Reverse Recovery Time	I <sub>F</sub> =3A, dI/dt=100A/μs	-	21	-	ns
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge		-	22	-	nC

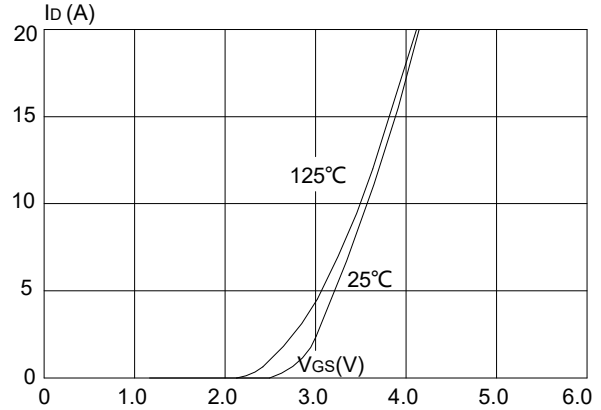
Notes: 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature  
2. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%

RATING AND CHARACTERISTIC CURVES

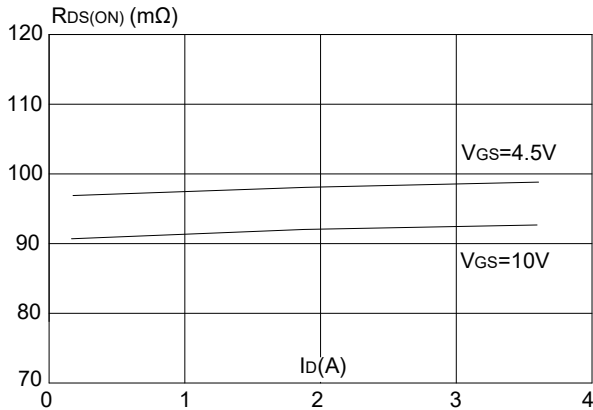
**Figure 1: Output Characteristics**



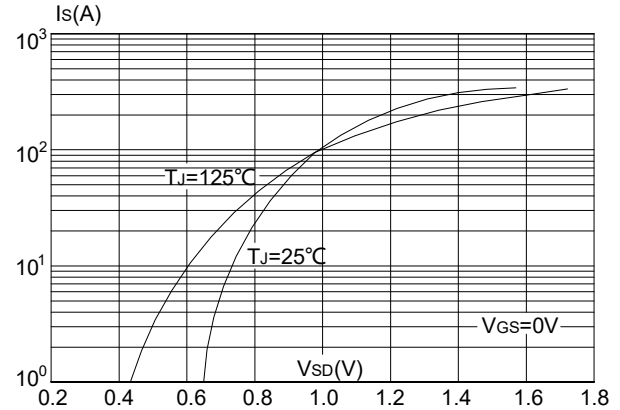
**Figure 2: Typical Transfer Characteristics**



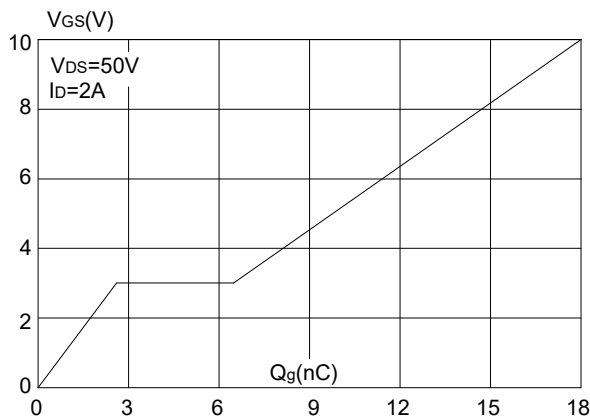
**Figure 3: On-resistance vs. Drain Current**



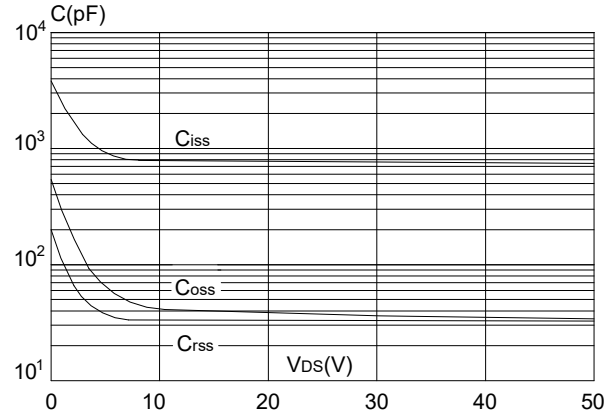
**Figure 4: Body Diode Characteristics**



**Figure 5: Gate Charge Characteristics**

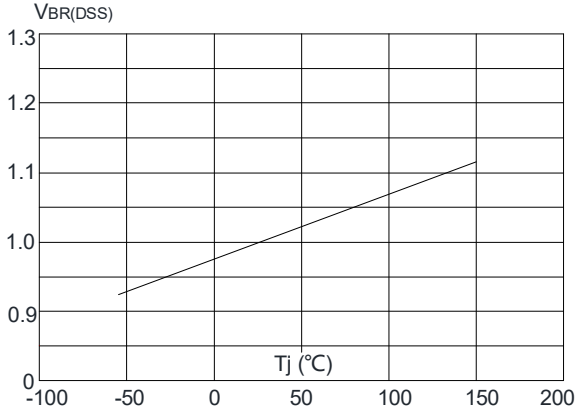


**Figure 6: Capacitance Characteristics**

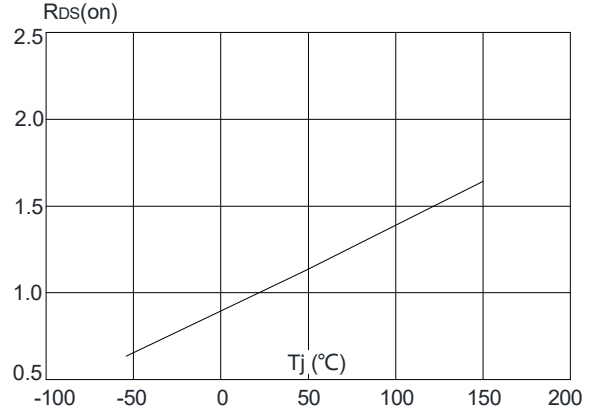


**RATING AND CHARACTERISTIC CURVES**

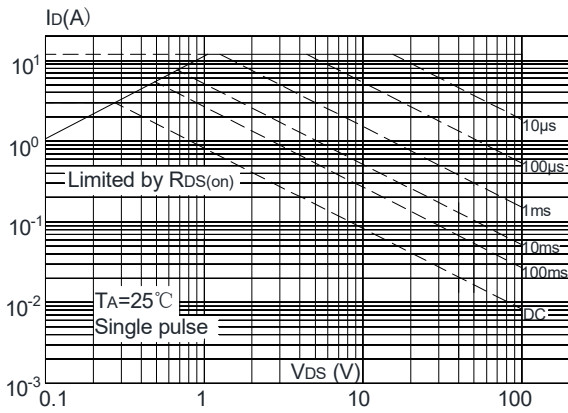
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



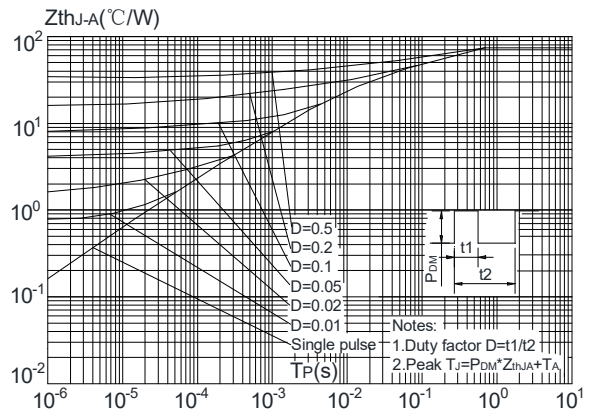
**Figure 8:** Normalized on Resistance vs. Junction Temperature



**Figure 9:** Maximum Safe Operating Area

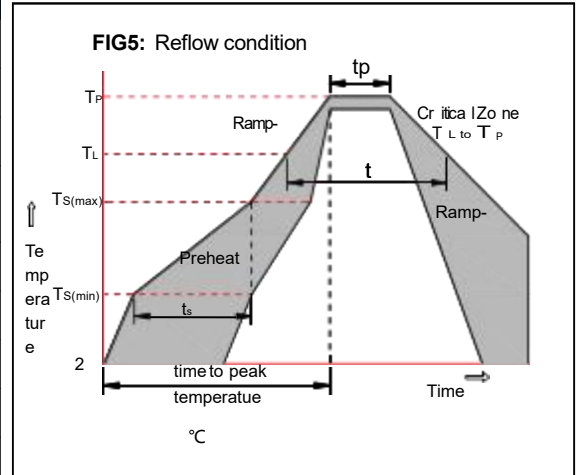


**Figure 10:** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



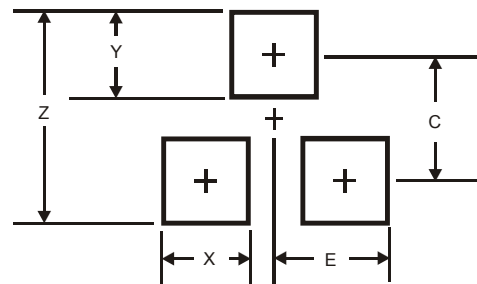
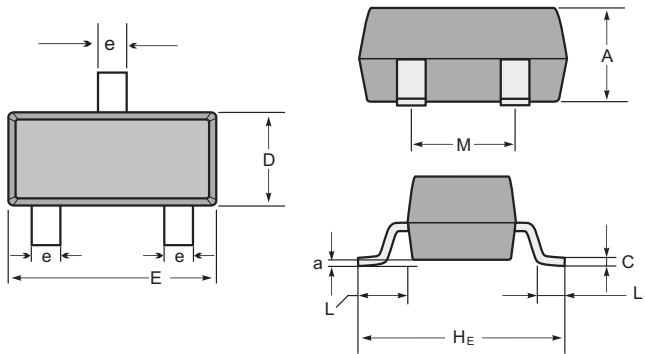
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ( $T_{s(min)}$ )	+150°C
	-Temperature Max( $T_{s(max)}$ )	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp ( $T_L$ ) to peak)		3°C/sec. Max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature( $T_L$ )(Liquid us)	+217°C
	-Temperature( $t_L$ )	60-150 secs.
Peak Temp ( $T_P$ )		+260(+0/-5)°C
Time within 5°C of actual Peak Temp ( $t_p$ )		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp ( $T_P$ )		8 min. Max
Do not exceed		+260°C



Package Dimensions & Suggested Pad Layout

SOT23



SOT-23 mechanical data

UNIT	A	C	D	E	HE	e	M	L	L1	a	
mm	max	1.1	0.15	1.4	3.0	2.6	0.5	1.95	0.55 (ref)	0.36 (ref)	0.0
	min	0.9	0.08	1.2	2.8	2.2	0.3	1.7			0.15
mil	max	43	6	55	118	102	20	77	22 (ref)	14 (ref)	0.0
	min	35	3	47	110	87	12	67			6

Dimensions	SOT23
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35

Tape & reel specification

Tape		Symbol	Dimension (mm)		
		P0	4.00±0.10		
		P1	4.00±0.10		
		P2	2.00±0.10		
		D0	1.55±0.10		
		D1	1.05±0.10		
		E	1.55±0.10		
		F	3.60±0.10		
		W	8.00±0.10		
		A0	3.80±0.20		
		B0	3.25±0.20		
		K0	1.45±0.10		
		T	0.25±0.05		
		7" Reel		D2	178.0±3.0
				D3	55Min.
				D4	R24.0±3.0
G	R82.0±3.0				
I	13.0±2.0				
W1	11.0±3.0				
		Quantity: 3000PCS			